

# ANALOG & CONNECTIVITY

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RENESAS ELECTRONICS CORPORATION

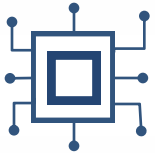
# AT A GLANCE

## ANALOG & CONNECTIVITY

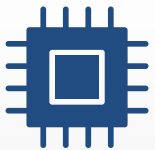
### Our products / technologies



Full system solution of memory interface products for DDR5



Broadest and deepest silicon timing portfolio

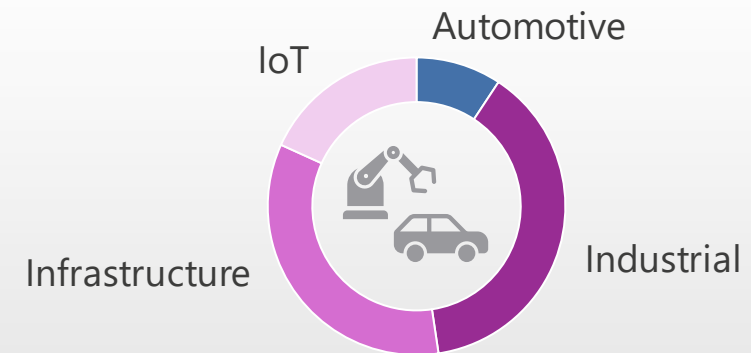
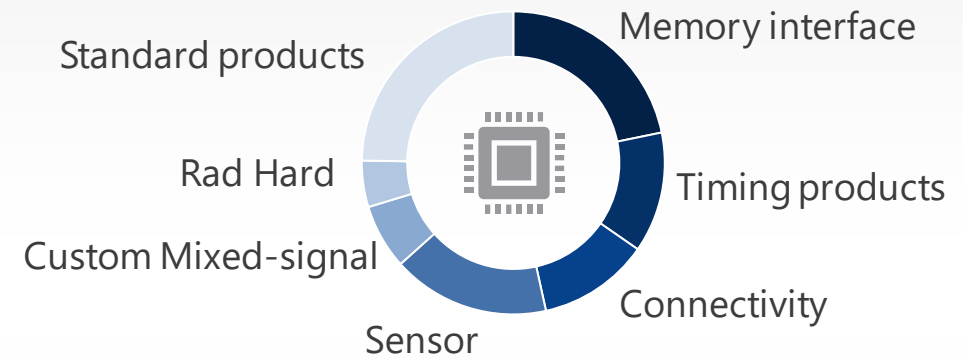


Connectivity (BLE, Wi-Fi, NFC, DECT, Sub-GHz, PLC etc.)



Sensors and sensor signal conditioners

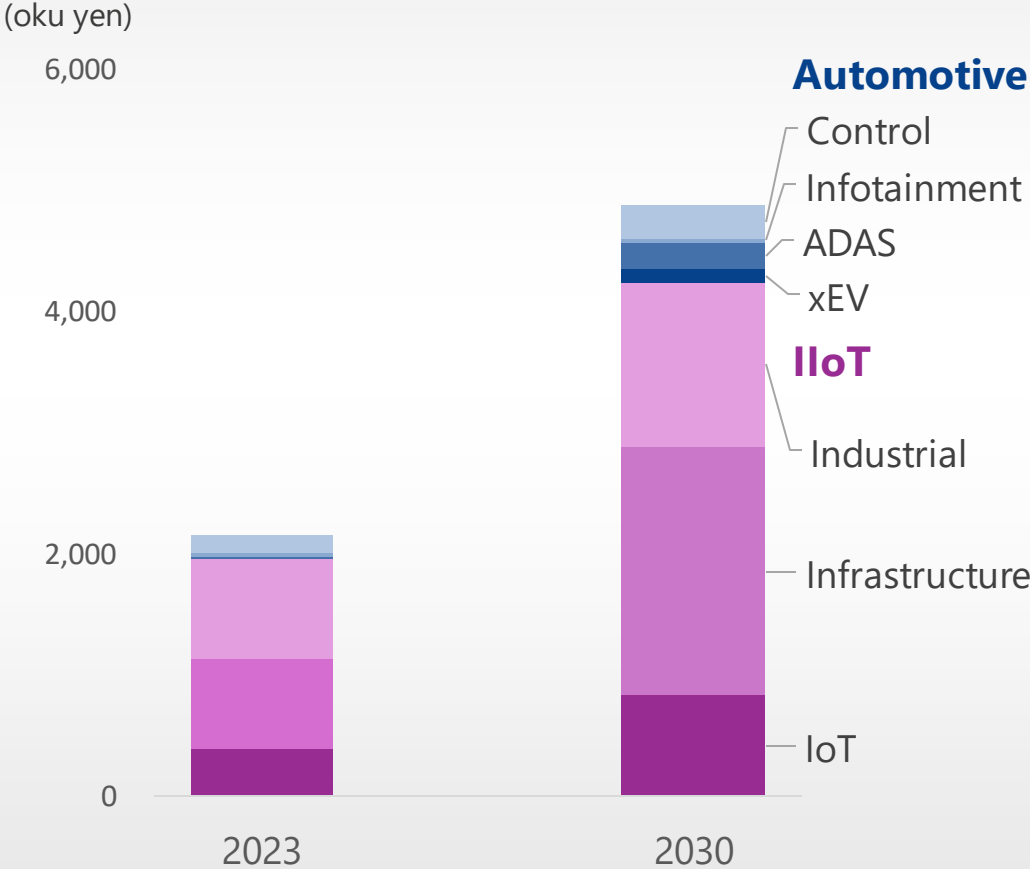
### 2023 Revenue



# GROWTH DRIVERS

## ANALOG & CONNECTIVITY

### Revenue



\* FX \$1 = 100yen, €1 = 120yen

### Growth drivers

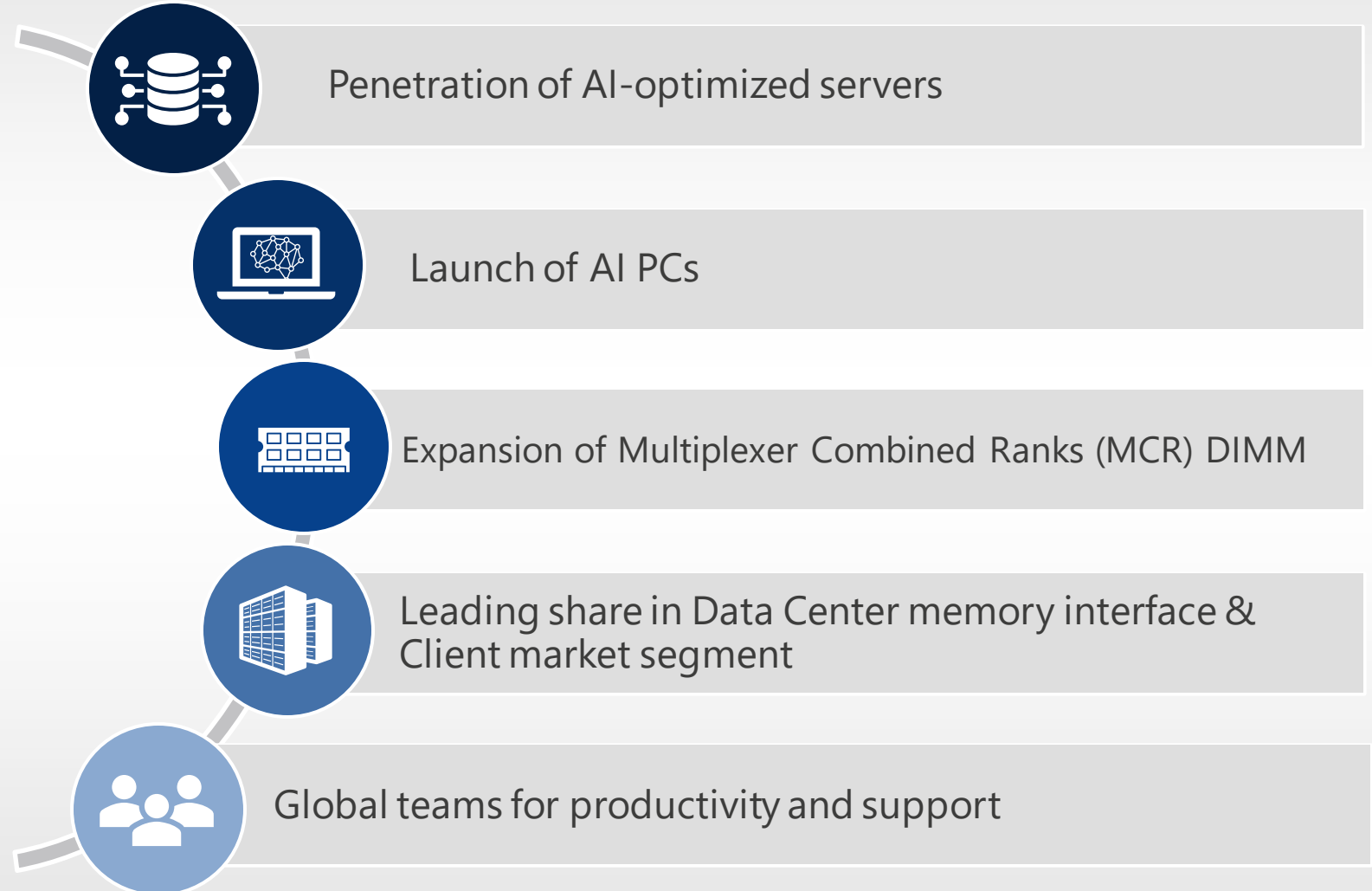
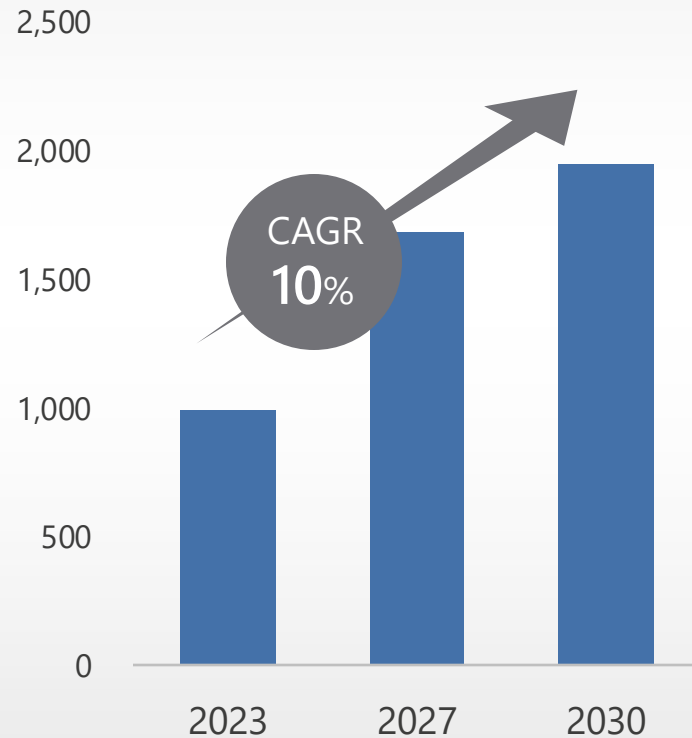
	<b>Automotive</b>	➤ Connectivity (NFC, UWB, BLE), Sensors, GreenPAK
	<b>Industrial</b>	➤ Solution Sell in Mass Market: GreenPAK/FPGAs, Standard products, Connectivity & Sensors
	<b>Infrastructure</b>	➤ Market leadership & content expansion in DDR5 and MCR solution
	<b>IoT</b>	➤ Low power, intelligent Connectivity solutions ideally suited for edge IoT

MCR: Multiplexer Combined Ranks, NFC: Near Filed Communication, UWB: Ultra Wide Band, BLE Bluetooth Low Energy

# MEMORY INTERFACE OVERVIEW

## Memory Interface Market

(oku yen)



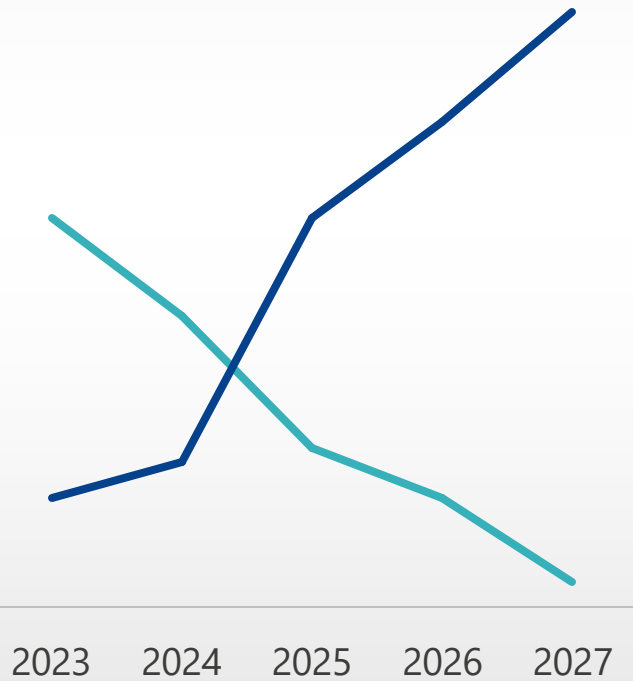
Source: Renesas estimates  
\* FX \$1 = 100yen, €1 = 120yen

# RENESAS MEMORY LEADING DDR5 TRANSITION

## EXPANDING CHIPSET CONTENT

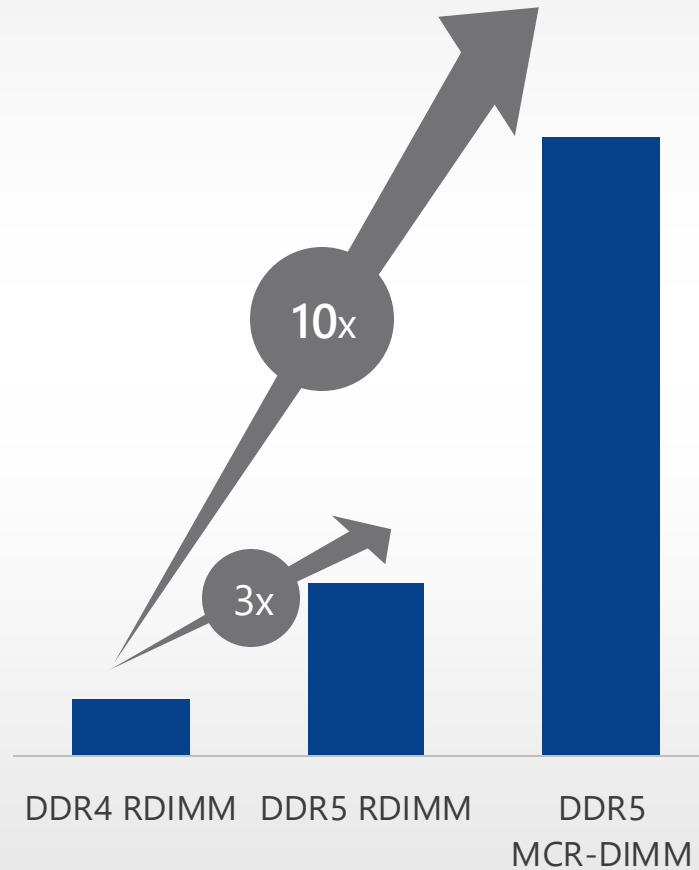
### DDR5 DIMM RAMP

— DDR4 server system  
— DDR5 server system



Source: Renesas estimates

### Chipset content (\$)



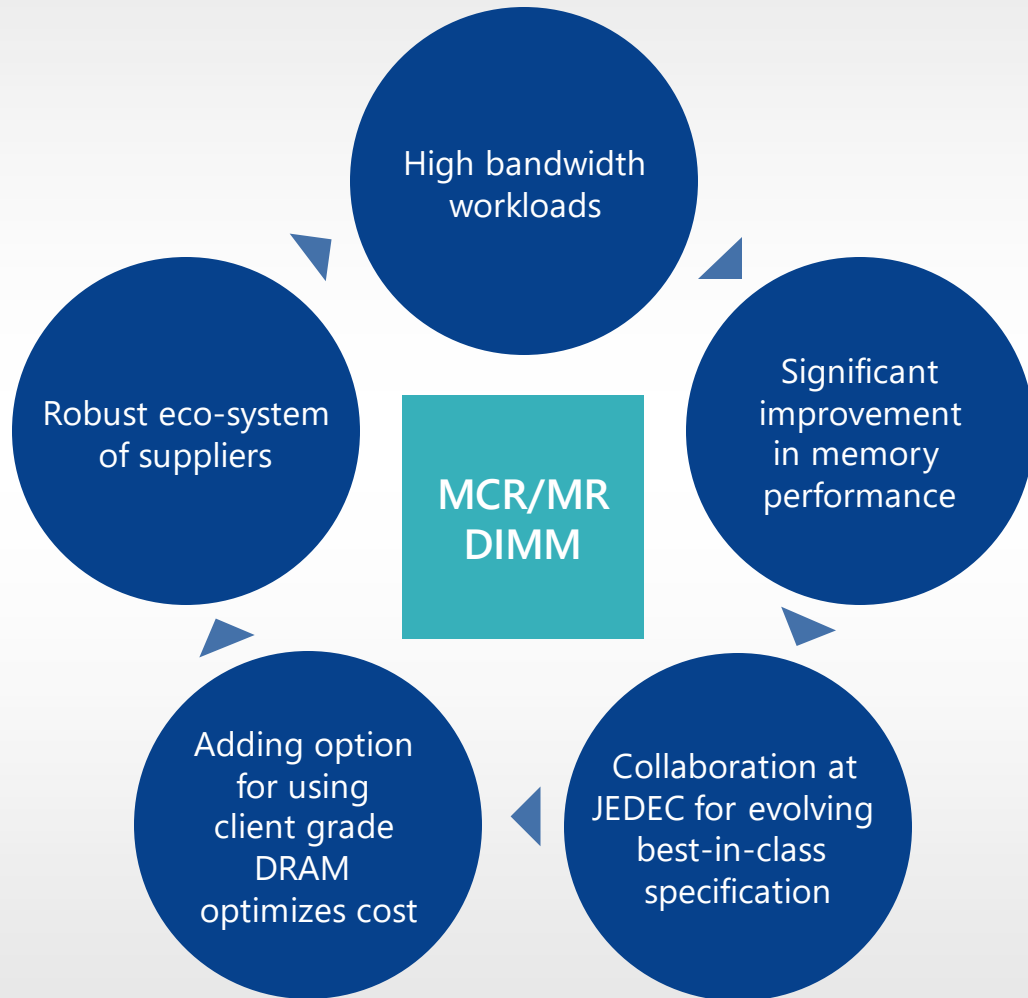
Source: Renesas estimates

### Comprehensive DDR5 Chip Set

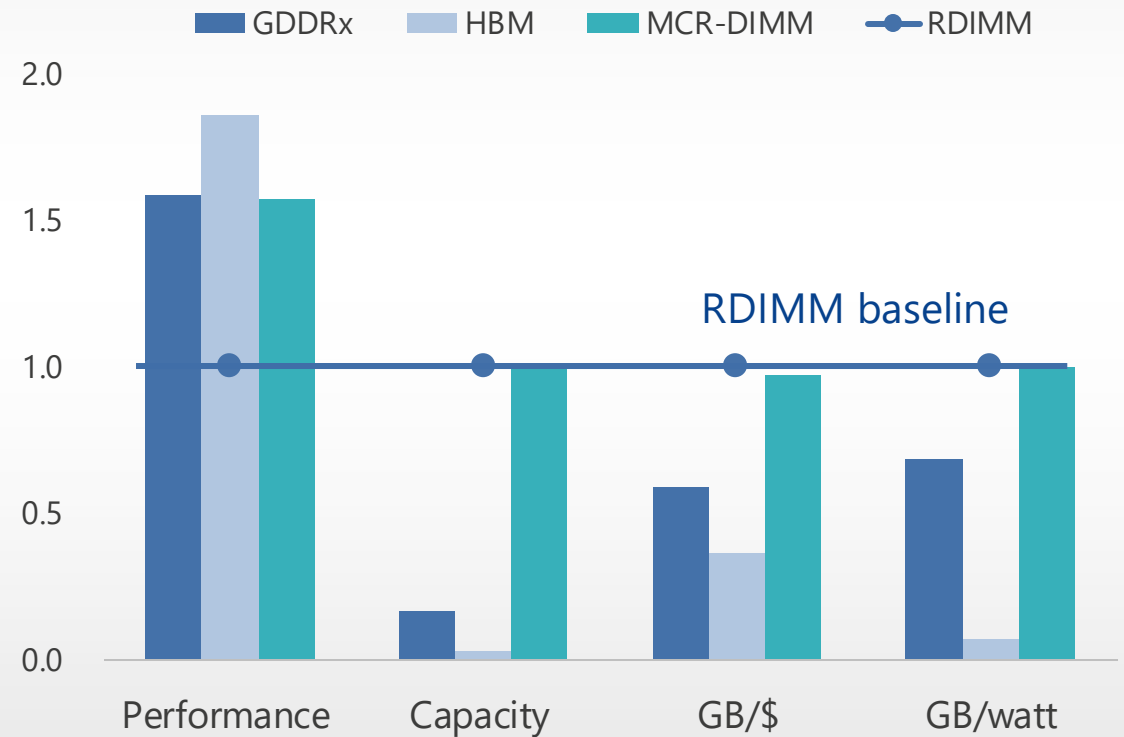
- PMIC
- Temp Sensor
- SPD Hub
- Registered Clock Driver
- Data Buffer

# NEW CLASS OF HIGH BANDWIDTH SOLUTIONS: MCR/MR DIMM

## OPTIMIZED SOLUTION FOR SYSTEM MEMORY IMPROVEMENT



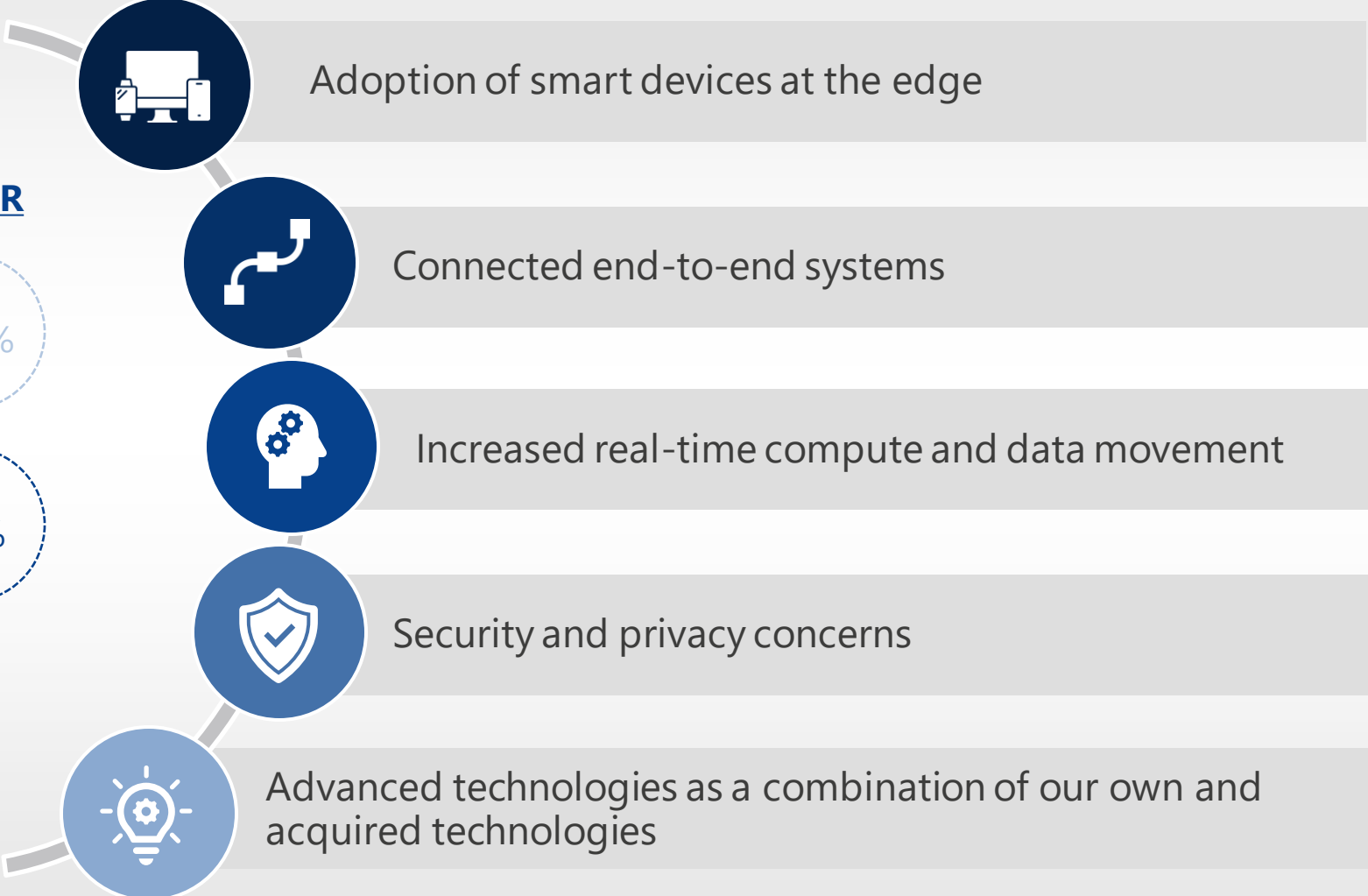
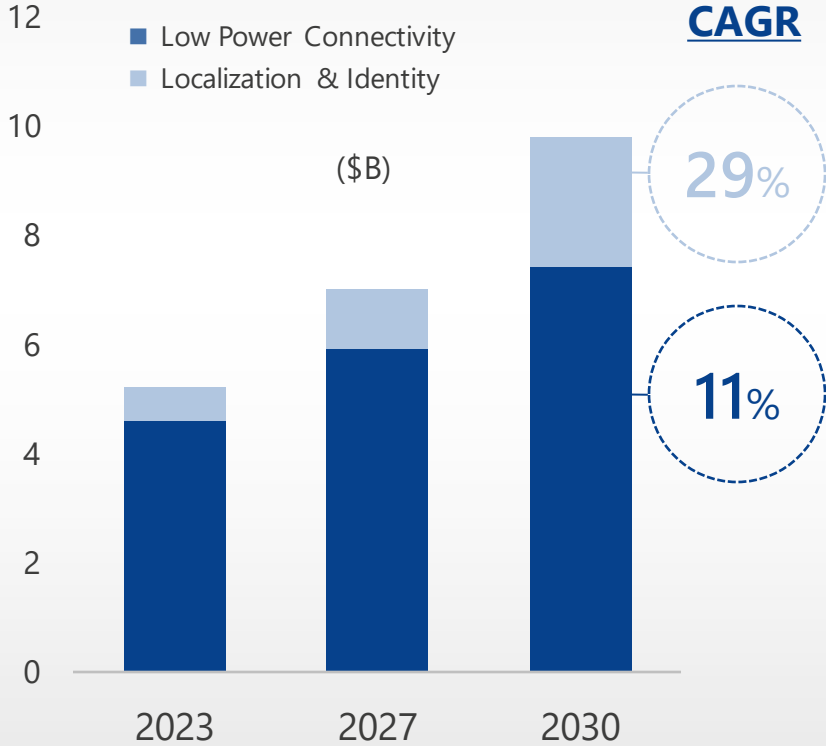
Comparison\*<sup>1</sup> of High bandwidth technologies  
(Relative to RDIMM baseline)



\*1: All metrics are estimated per SoC from various sources

# CONNECTIVITY OVERVIEW

## Connectivity SAM



Source: Renesas estimates

# CONNECTIVITY @ THE EDGE - SCALABLE STRATEGY

## Challenges



Low power budgets



Data integrity



Real-time responses

## Scalable strategy



Ultra low power architecture



Localization & Identity connectivity




Software platform



# CONNECTIVITY @ THE EDGE - COMPETITIVE ADVANTAGE

## Low Power @ the edge

Leveraging Renesas unique architecture delivering up to **50%** less power than the nearest competitor in class


 >2yrs on 2 AA batteries

 10yrs on CR2032 cell




## Reduced cost of ownership

Integration of key components to reduce BOM

 Reducing customer board size by 30%


 Integration of Power Management & MCU

 Removal of complex matching circuitry

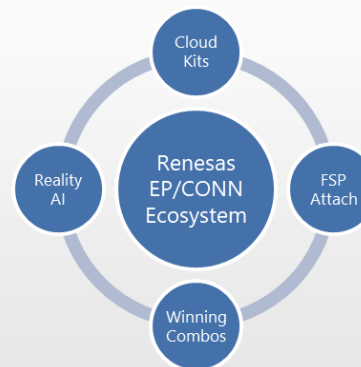
## Performance where it matters

Functional & performance advantages for key customer needs

 Enabling secure access with widest margin

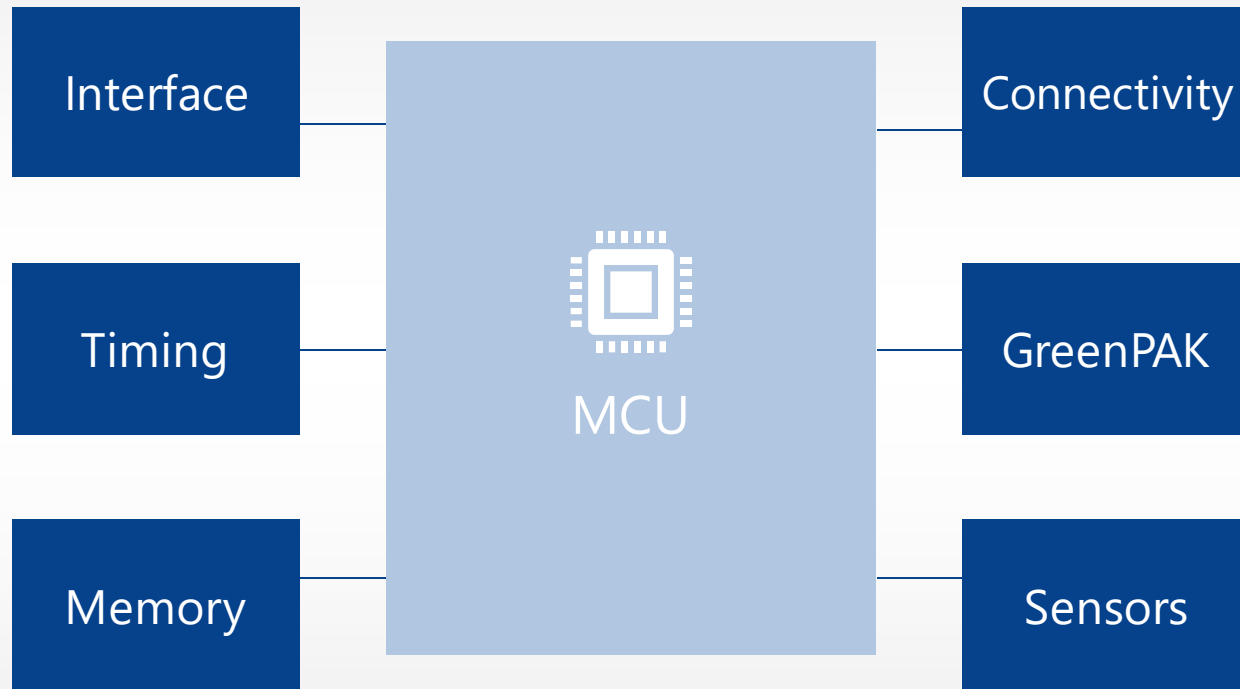
 Double the interference robustness of nearest competition in noisy environments

## Scalable integration with MCU



Seamless integration into the Renesas EP ecosystem significantly reduces development time

# SOLUTION SELL



**> 500<sup>\*1</sup>**  
of Winning Combo's

**~ 3,000<sup>\*2</sup>** oku yen / year  
of potential SAM expansion

\*1: Numbers based on the launch until the end of 2023, \*2: Renesas estimates

# SUMMARY



DDR5 / MCR ramp and content increase driving memory interface growth

Connectivity products ideally suited to address market demands as connectivity at the edge increases

Solution sell leveraging MCU market share & broad product portfolio

Ease of use software platform enabling faster market adoption





THANK YOU

(FORWARD-LOOKING STATEMENTS)

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